

IN THE CLAIMS

Please amend claims 1 and 7 as follows:

SUB
B1 7
A2

1. (Amended) A semiconductor device, comprising:
a plurality of semiconductor chips mounted on an outer surface of a substrate;
an insulation film provided on said substrate, wherein a top surface and side surfaces of
said plurality of semiconductor chips are encrusted in said insulation film; and
wiring provided on said insulation film, wherein said wiring is connected to said plurality
of semiconductor chips through a connection hole formed on said insulation film.

SUB
B2 7
A3

7. (Amended) A semiconductor device, comprising:
a plurality of semiconductor chips;
an insulation layer supporting said plurality of semiconductor chips, wherein a top surface
and at least a portion of side surfaces of said plurality of semiconductor chips are encrusted in
said insulation layer and a surface opposite said top surface of said plurality of semiconductor
chips is exposed; and
wiring provided on said insulation layer, wherein said wiring is connected to each
semiconductor chip of said plurality of semiconductor chips through a connection hole formed
on said insulation layer.